



(51) International Patent Classification:

G06N 10/00 (2019.01) H01L 25/00 (2006.01)
H01L 21/00 (2006.01) H01L 27/00 (2006.01)
H01L 23/00 (2006.01)

(21) International Application Number:

PCT/EP2021/056078

(22) International Filing Date:

10 March 2021 (10.03.2021)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

16/835,862 31 March 2020 (31.03.2020) US

(71) Applicant: **INTERNATIONAL BUSINESS MACHINES CORPORATION** [US/US]; New Orchard Road, Armonk, New York 10504 (US).

(71) Applicant (for MG only): **IBM DEUTSCHLAND GMBH** [DE/DE]; IBM-Allee 1, 71139 Ehningen (DE).

(72) Inventors: **SHAO, Dongbing**; c/o IBM Thomas J Watson Research Center, 1101 Kitchawan Road, Route 134, P.O. Box 218, Yorktown Heights, New York 10598 (US). **LEWANDOWSKI, Eric**; c/o IBM Thomas J Watson Research Center, 1101 Kitchawan Road, Route 134, P.O. Box 218, Yorktown Heights, New York 10598 (US). **BRONN, Nicholas**; c/o IBM Thomas J Watson Research Center, 1101 Kitchawan Road, Route 134, P.O. Box 218, Yorktown Heights, New York 10598 (US). **BRINK, Markus**; c/o IBM Thomas J Watson Research Center, 1101 Kitchawan Road, Route 134, P.O. Box 218, Yorktown Heights, New York 10598 (US).

(74) Agent: **LAUX, Felix**; c/o IBM Deutschland GmbH, Patentwesen und Urheberrecht, IBM-Allee 1, 71139 Ehningen (DE).

(54) Title: HYBRID READOUT PACKAGE FOR QUANTUM MULTICHIP BONDING

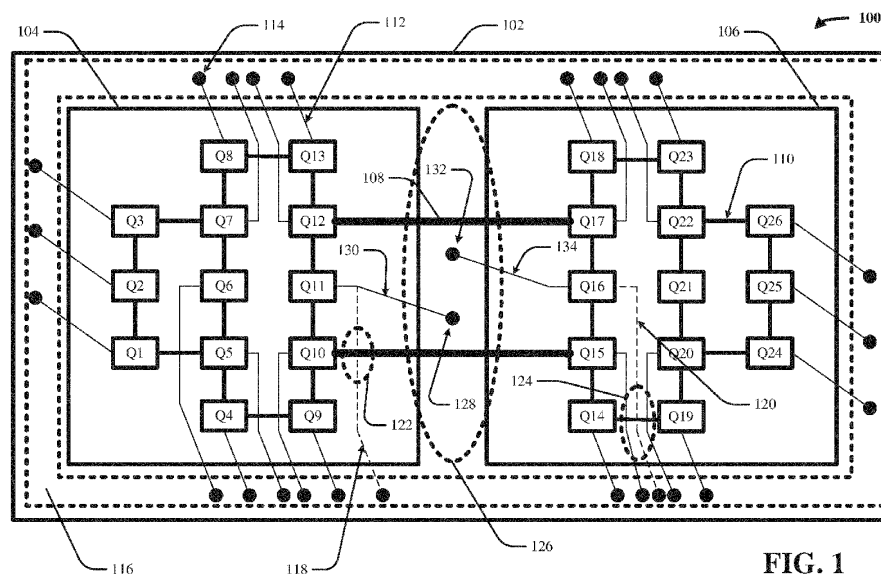


FIG. 1

(57) Abstract: Systems and techniques that facilitate hybrid readout packaging for quantum multichip bonding are provided. In various embodiments, an interposer can have a first quantum chip and a second quantum chip. In various aspects, a readout resonator (e.g., input/output port) of one or more qubits on the first quantum chip can be routed to an inner portion of the interposer. In various instances, the inner portion can be located between the first quantum chip and the second quantum chip. In various aspects, routing the readout resonator to the inner portion can reduce a number of crossings and/or intersections between input/output lines on the interposer and connection buses between qubits on the interposer.

[Continued on next page]

(81) Designated States (*unless otherwise indicated, for every kind of national protection available*): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DJ, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IR, IS, IT, JO, JP, KE, KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS, ZA, ZM, ZW.

(84) Designated States (*unless otherwise indicated, for every kind of regional protection available*): ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, ST, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Published:

— with international search report (Art. 21(3))